

PATENT  
81754.0114  
Express Mail Label No. EV 324 112 472 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Terunao HANAOKA et al.

Serial No: Not assigned

Filed: March 17, 2004

For: Semiconductor Wafer, Semiconductor Device and  
Method for Manufacturing Same, Circuit Board, and  
Electronic Apparatus

Art Unit: Not assigned

Examiner: Not assigned

**TRANSMITTAL OF INFORMATION DISCLOSURE  
STATEMENT**

Mail Stop PATENT APPLICATION  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

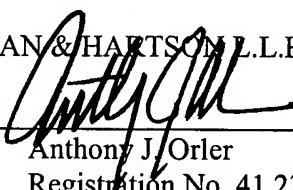
Dear Sir:

The information disclosure statement submitted herewith is being filed concurrently with the subject application [37 C.F.R. § 1.97(b)] and contains no items of information cited in any communication from a foreign patent office in a counterpart foreign application [37 C.F.R. § 1.97(e)(1)].

If it should be determined that for any reason either an insufficient or excessive fee has been paid, please charge any insufficiency or credit any overpayment necessary to ensure consideration of the information disclosure statement for the above-identified application to Deposit Account No. 50-1314. A copy of this paper is enclosed.

Respectfully submitted,

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